



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-08-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BTLM*A6C088T	A	Z8GA	2015-08-07
Amount	UoM	Unit type	ST ECOPACK Grade	
110.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	3.5- 6.5 - 1.8	4	gull wing	
Comment	Package: SOT 223 PLANAR and TOPGLASS; MDF valid for ACS108-8TN-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BTLM*A6C08BT					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	1.183	mg	supplier	die	Silicon (Si)	7440-21-3		1.133	mg	957735	10300
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.037	mg	31276	336
Silicon die				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	845	9
Silicon die				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1691	18
Silicon die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.01	mg	8453	91
Leadframe	Copper & its alloys	58.552	mg	supplier	alloy	Copper(Cu)	7440-50-8		57.765	mg	986559	525136
Leadframe				supplier	alloy	Iron(Fe)	7439-89-6		0.058	mg	991	527
Leadframe				supplier	alloy	Phosphorus(P)	12185-10-3		0.017	mg	290	155
Leadframe				supplier	metallization	Silver(Ag)	7440-22-4		0.712	mg	12160	6473
Soft solder	Solder	1.498	mg	JIG - R	solder	Lead(Pb)	7439-92-1	7a-Lead in high me	1.43	mg	954606	13000
Soft solder				supplier	solder	Silver(Ag)	7440-22-4		0.038	mg	25367	345
Soft solder				supplier	solder	Tin(Sn)	7440-31-5		0.03	mg	20027	273
Bonding wire	Other Inorganic Material	0.154	mg	supplier	wire	Copper(Cu)	7440-50-8		0.154	mg	1000000	1400
encapsulation	Other Inorganic Material	47.573	mg	supplier	mold compound	Silica Fused	60676-86-0		41.866	mg	880037	380600
encapsulation				supplier	mold compound	Epoxy,Cresol Novolac	29690-82-2		0.713	mg	14987	6482
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		2.378	mg	49986	21618
encapsulation				supplier	mold compound	Epoxy Resin	Proprietary		2.378	mg	49986	21618
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.238	mg	5003	2164
connections coating	Solder	1.04	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.04	mg	1000000	9455